2SJ0164 (2SJ164)

Silicon P-Channel Junction FET

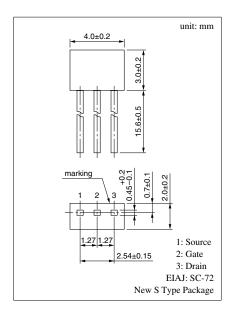
For switching Complementary to 2SK1104

■ Features

- Low ON-resistance
- Low-noise characteristics

■ Absolute Maximum Ratings (Ta = 25°C)

| Parameter | Symbol | Ratings | Unit |
|-----------------------------|------------------|-------------|------|
| Gate to Drain voltage | V _{GDS} | 65 | V |
| Drain current | I_{D} | -20 | mA |
| Gate current | I_{G} | -10 | mA |
| Allowable power dissipation | P_{D} | 300 | mW |
| Channel temperature | T _{ch} | 150 | °C |
| Storage temperature | T _{stg} | -55 to +150 | °C |



■ Electrical Characteristics (Ta = 25°C)

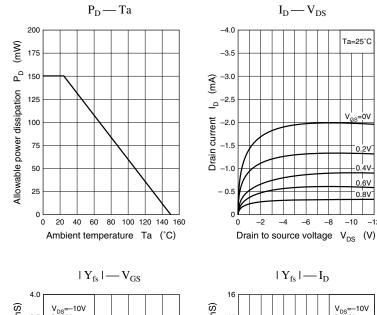
| Parameter | Symbol | Conditions | min | typ | max | Unit |
|--|---------------------|---|-------|-----|-----|------|
| Drain to Source cut-off current | ${\rm I_{DSS}}^*$ | $V_{DS} = -10V, V_{GS} = 0$ | - 0.2 | | -6 | mA |
| Gate to Source leakage current | I_{GSS} | $V_{GS} = 30V, V_{DS} = 0$ | | | 10 | nA |
| Gate to Drain voltage | V_{GDS} | $I_{G} = 10\mu A, V_{DS} = 0$ | 65 | | | V |
| Gate to Source cut-off voltage | V_{GSC} | $V_{DS} = -10V, I_{D} = -10\mu A$ | | 1.5 | 3.5 | V |
| Forward transfer admittance | Y _{fs} | $V_{DS} = -10V, I_{D} = -1mA, f = 1kHz$ | 1.8 | 2.5 | | mS |
| Drain to Source ON-resistance | R _{DS(on)} | $V_{DS} = -10 \text{mV}, V_{GS} = 0$ | | 300 | | Ω |
| Input capacitance (Common Source) | C _{iss} | | | 10 | | pF |
| Output capacitance (Common Source) | C _{oss} | $V_{DS} = -10V, V_{GS} = 0, f = 1MHz$ | | 3 | | pF |
| Reverse transfer capacitance (Common Source) | C_{rss} | | | 3 | | pF |

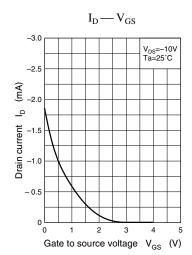
 $^{^*}$ I_{DSS} rank classification

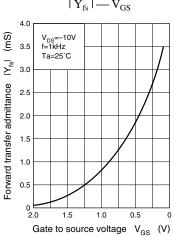
| Runk | О | P | Q | R |
|-----------------------|-------------|---------------|----------|------------|
| I _{DSS} (mA) | - 0.2 to -1 | - 0.6 to -1.5 | −1 to −3 | −2.5 to −6 |

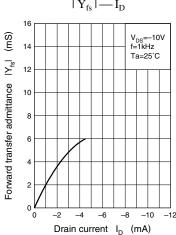
Note) The part number in the parenthesis shows conventional part number.

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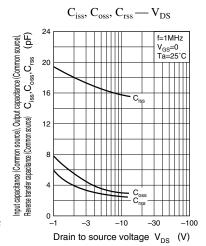


Ta=25°C

0.6V

0.8V

-10



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